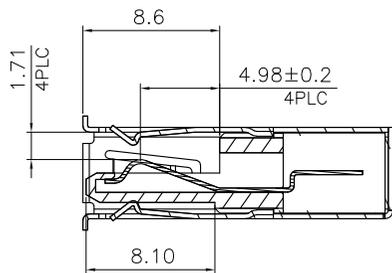
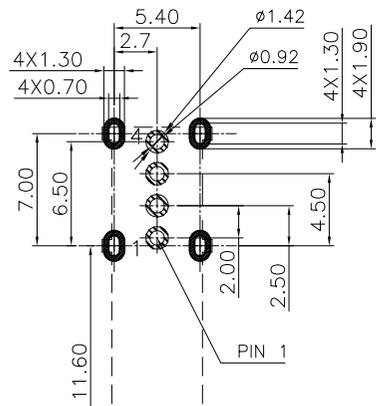
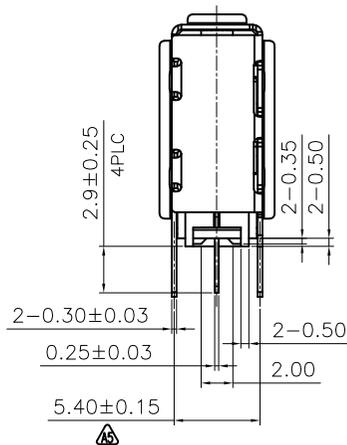
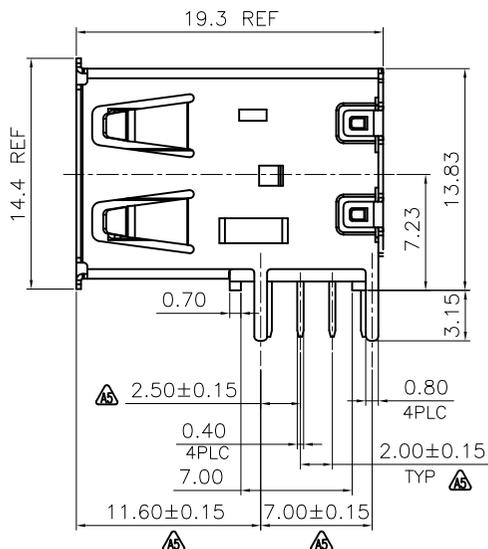
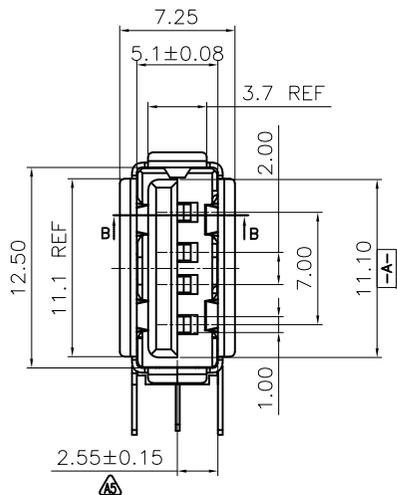
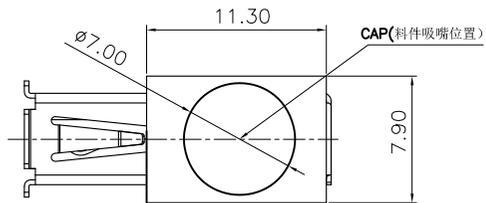


GP Component



PROFILE OF CONECTOR
SOLDER AREA

RECOMMEND P.C.BOARD LAYOUT
PCB TOLERANCE:±0.05

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/10/06	Phebe Su
A1			Change	2015/12/11	Phebe Su
A2			Change CAP and Layout	2016/05/12	Phebe Su
A3			Change	2018/01/05	Phebe Su
A4			Change	2018/01/29	Phebe Su
A5			Change DIM. Tolerance	2023/07/17	Ken Lin

NOTES:

1.MATERIAL:

- 1.1 HOUSING: LCP E130i UL 94V-0 COLOR: BLACK
- 1.2 SPACER: HIGH TEMPERATURE THERAL PLASTIC, LCP COLOR: BLACK
- 1.3 CONTACT: COPPER ALLOY.
- 1.4 SHELL: SUS201.

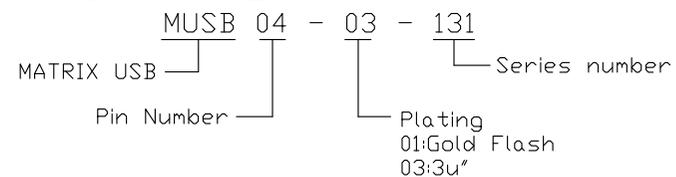
2.FINISH:

- 2.1 CONTACT: GOLD 3u" ON CONTACT AREA/100μ" Min TIN ON SOLDER AREA, 80μ" MIN. NICKEL UNDERPLATING OVER ALL.
- 2.2 SHELL: 50μ" MIN.NIKEL PLATING OVERALL.

3.ELECTRICAL:

- 3-1.CURRENT RATING 1.5A/CONTACT TERMINAL
 - 3-2.VOLTAGE RATING 30V DC
 - 3-3.CONTACT RESISTANCE 30 MILLIOHMS MAX
 - 3-4.DIELECTNIC WITHSTANDING VOITAGE:500 V AC AT SEA LEVEL
 - 3-5.INSULATION RESISTANCE:1000MEGA OHMS MIN
 - 3-6.MATE FORCE:3.75KGF(MAX),UNMATE FORCE:0.8KGF(MIN)
 - 3-7.TERMINAL RETENION 0.4KGF(MIN)
 - 3-8.OPERATION TEMPERATURE : -40°C~+85°C
- 4.THIS MATERIAL COMPLIES WITH PIP.

MATRIX PART NO:



PIN NO.	PIN 1	PIN 2	PIN 3	PIN 4
SLGNL NAME	V BUS	D-	D+	GND



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.05 ANGLE: ±3°	DESIGN BY : Ken Lin	DATE : 2023/07/17	PART NAME: USB 2.0母座側向 90° DIP TYPE	
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY: Janice Liu	DATE : 2023/07/17	PART NO.	MUSB04-03-131
	APPROVED BY1: Richard Hsieh	DATE : 2023/07/17	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2023/07/17	DRAW NO.	
			SHEET NO.	1 OF 1